

## IGBT - Power, Single N-Channel, Field Stop VII (FS7), SCR, Power TO247-3L

1200 V, 1.45 V, 40 A

## AFGHL40T120RW

### **Description**

Using the novel field stop 7th generation IGBT technology in TO247 3-lead package, this device offers the optimum performance with low on state voltage and minimal switching losses for both hard and soft switching topologies in automotive applications.

#### **Features**

- Extremely Efficient Trench with Field Stop Technology
- Maximum Junction Temperature T<sub>J</sub> =175°C
- Short Circuit Rated / Low Saturation Voltage
- Fast Switching / Tightened Parameter Distribution
- AEC-Q101 Qualified, PPAP Available Upon Request
- This Device is Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### **Applications**

- Automotive E-compressor
- Automotive EV PTC Heater
- OBC

## **MAXIMUM RATINGS** (T<sub>J</sub> = 25°C unless otherwise noted)

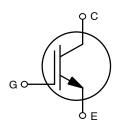
Paran	Symbol	Value	Unit	
Collector-to-Emitter Vol	V <sub>CE</sub>	1200	V	
Gate-to-Emitter Voltage	)	$V_{GE}$	±20	
Transient Gate-to-Emit	er Voltage	1	±30	
Collector Current	T <sub>C</sub> = 25°C	Ic	80	Α
	T <sub>C</sub> = 100°C		40	
Power Dissipation T <sub>C</sub> = 25°C		$P_{D}$	652	W
	T <sub>C</sub> = 100°C	1	326	
$ \begin{array}{ccc} \text{Pulsed Collector} & & & & & & \\ \text{Current} & & & & & \\ & & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & &$		I <sub>CM</sub>	120	Α
Short Circuit Withstand V <sub>GE</sub> = 15 V, V <sub>CC</sub> = 800 V	T <sub>SC</sub>	6	μs	
Operating Junction and Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	
Lead Temperature for So	$T_L$	260		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1

BV <sub>CES</sub>	V <sub>CE(sat)</sub> TYP	I <sub>C</sub> MAX
1200 V	1.45 V	40 A

#### **PIN CONNECTIONS**





#### **MARKING DIAGRAM**



AFGH40120RW = Specific Device Code

&Z = Assembly Plant Code

&3 = 3-Digit Date Code

&K = 2-Digit Lot Traceability Code

\$Y = onsemi Logo

### **ORDERING INFORMATION**

Device	Package	Shipping
AFGHL40T120RW	TO-247-3L (Pb-Free)	30 Units / Tube

<sup>1.</sup> Repetitive rating: Pulse width limited by max. junction temperature

## THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case for IGBT	$R_{ heta JC}$	0.23	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{ hetaJA}$	40	

## **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS				-		•
Collector-to-Emitter Breakdown Voltage	BV <sub>CES</sub>	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 1 mA	1200	-	-	V
Zero Gate Voltage Collector Current	I <sub>CES</sub>	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = V <sub>CES</sub>	-	-	40	μΑ
Gate-to-Emitter Leakage Current	I <sub>GES</sub>	V <sub>GE</sub> = ±20 V, V <sub>CE</sub> = 0 V	-	-	±400	nA
ON CHARACTERISTICS						
Gate-to-Emitter Threshold Voltage	V <sub>GE(th)</sub>	$V_{GE} = V_{CE}$ , $I_C = 40 \text{ mA}$	4.98	5.88	6.78	V
Collector-to-Emitter Saturation	V <sub>CE(sat)</sub>	V <sub>GE</sub> = 15 V, I <sub>C</sub> = 40 A, T <sub>J</sub> = 25°C	-	1.45	1.78	V
Voltage		V <sub>GE</sub> = 15 V, I <sub>C</sub> = 40 A, T <sub>J</sub> = 175°C	-	1.75	-	]
DYNAMIC CHARACTERISTICS						
Input Capacitance	C <sub>IES</sub>	V <sub>CE</sub> = 30 V, V <sub>GE</sub> = 0 V, f = 1 MHz	_	4717	-	pF
Output Capacitance	C <sub>OES</sub>		_	144	-	1
Reverse Transfer Capacitance	C <sub>RES</sub>		_	24.5	-	
Total Gate Charge	$Q_{G}$	V <sub>CE</sub> = 600 V, V <sub>GE</sub> = 15 V, I <sub>C</sub> = 40 A	_	171	-	nC
Gate-to-Emitter Charge	$Q_{GE}$		_	42.2	-	
Gate-to-Collector Charge	$Q_{GC}$		_	73.7	-	
SWITCHING CHARACTERISTICS, IN	DUCTIVE LOA	AD (Note: Si Diode Applied)				
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>CE</sub> = 600 V	-	50.1	=	ns
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GE} = 0/15 \text{ V}$ $I_{C} = 20 \text{ A}$	-	293	-	
Rise Time	t <sub>r</sub>	$R_G = 4.7 \Omega$ $T_J = 25^{\circ}C$	-	30.9	-	
Fall Time	t <sub>f</sub>		-	189	-	
Turn-On Switching Loss	E <sub>on</sub>		_	1.37	-	mJ
Turn-Off Switching Loss	E <sub>off</sub>		_	1.35	-	
Total Switching Loss	E <sub>ts</sub>		-	2.72	-	
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>CE</sub> = 600 V	=	55.2	-	ns
Turn-Off Delay Time	t <sub>d(off)</sub>	V <sub>GE</sub> = 0/15 V I <sub>C</sub> = 40 A	-	241	-	
Rise Time	t <sub>r</sub>	$R_G = 4.7 \Omega$ $T_A = 25^{\circ}C$	-	55.2	-	
Fall Time	t <sub>f</sub>		-	122	-	
Turn-On Switching Loss	E <sub>on</sub>	]	-	3.68	-	mJ
Turn-Off Switching Loss	E <sub>off</sub>	]	-	1.7	-	
Total Switching Loss	E <sub>ts</sub>	] [	-	5.38	-	1

## **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise specified) (continued)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
SWITCHING CHARACTERISTICS, INDUCTIVE LOAD (Note: Si Diode Applied)						
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>CE</sub> = 600 V	-	56	-	ns
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GE} = 0/15 \text{ V}$ $I_{C} = 20 \text{ A}$	=	414	-	1
Rise Time	t <sub>r</sub>	$R_G = 4.7 \Omega$ $T_{.l} = 175 ^{\circ}C$	=	41.7	-	1
Fall Time	t <sub>f</sub>	<b>10</b> 112 2	-	375	-	
Turn-On Switching Loss	E <sub>on</sub>		-	2.13	-	mJ
Turn-Off Switching Loss	E <sub>off</sub>		-	2.51	-	
Total Switching Loss	E <sub>ts</sub>		-	4.64	-	
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>CE</sub> = 600 V	-	63.1	-	ns
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GE}^{}=0/15 \text{ V}$ $I_{C}=40 \text{ A}$ $R_{G}=4.7 \Omega$ $T_{J}=175^{\circ}\text{C}$	-	325	-	
Rise Time	t <sub>r</sub>		-	71.2	-	
Fall Time	t <sub>f</sub>		-	233	-	1
Turn-On Switching Loss	E <sub>on</sub>		-	5.75	-	mJ
Turn-Off Switching Loss	E <sub>off</sub>		-	3.03	-	
Total Switching Loss	E <sub>ts</sub>		_	8.79	-	1

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **TYPICAL CHARACTERISTICS**

120

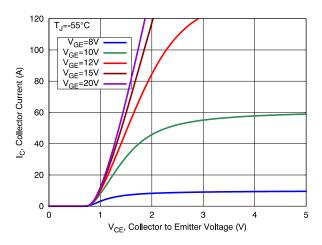
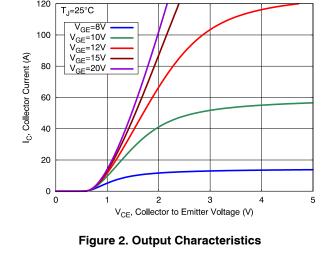


Figure 1. Output Characteristics



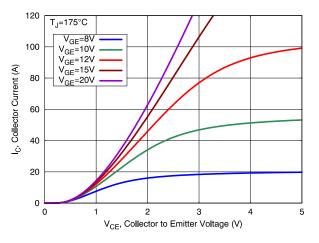


Figure 3. Output Characteristics

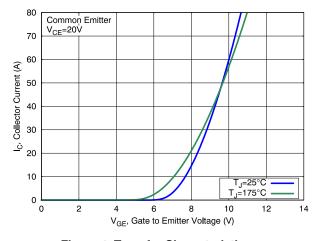


Figure 4. Transfer Characteristics

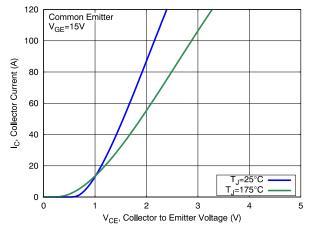


Figure 5. Saturation Characteristics

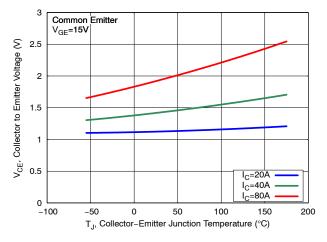


Figure 6. Saturation Voltage vs Junction Temperature

#### **TYPICAL CHARACTERISTICS**

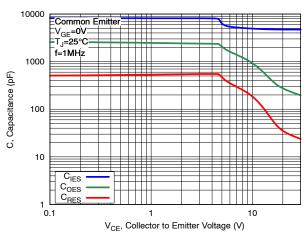


Figure 7. Capacitance Characteristics

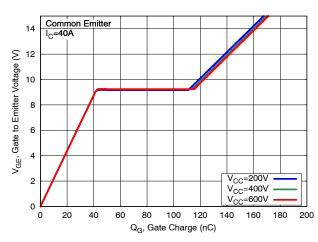


Figure 8. Gate Charge Characteristics

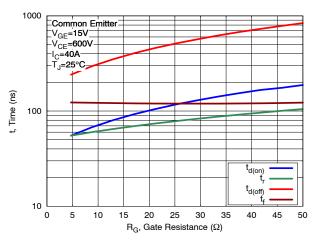


Figure 9. Switching Time vs Gate Resistance

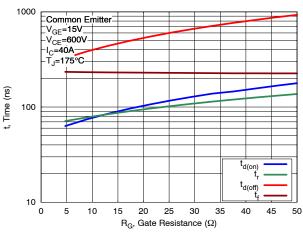


Figure 10. Switching Time vs Gate Resistance

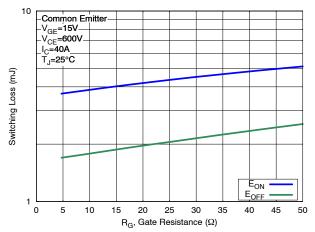


Figure 11. Switching Loss vs Gate Resistance

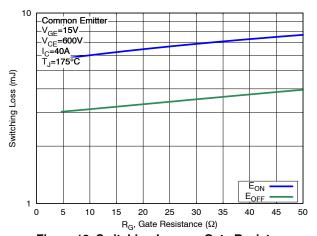
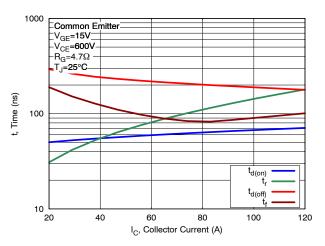


Figure 12. Switching Loss vs Gate Resistance

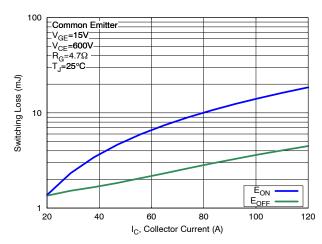
#### **TYPICAL CHARACTERISTICS**



1000 | Common Emitter | V<sub>GE</sub>=15V | V<sub>GE</sub>=600V | R<sub>G</sub>=4.7\( \Omega \) | -T<sub>J</sub>=175°C | | t<sub>d</sub>(on) | t<sub>d</sub>(off) | t<sub>d</sub>

Figure 13. Switching Time vs Collector Current

Figure 14. Switching Time vs Collector Current



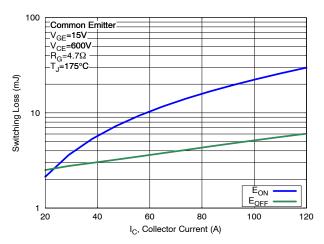


Figure 15. Switching Loss vs Gate Resistance

Figure 16. Switching Loss vs Collector Current

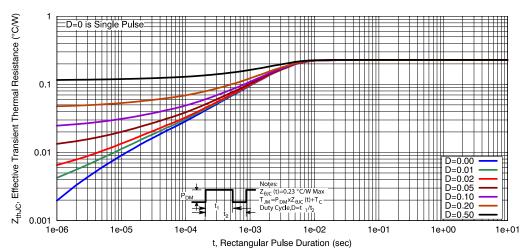
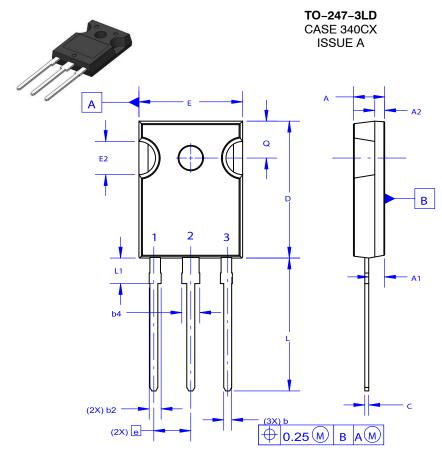


Figure 17. Transient Thermal Impedance of IGBT

**DATE 06 JUL 2020** 





NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

# GENERIC MARKING DIAGRAM\*



XXXXX = Specific Device Code A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present. Some products may not follow the Generic Marking.

Ø <sub>P</sub> —		Φ <sub>P1</sub> D2
E1 —	2	D1

DIM	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
<b>A</b> 1	2.20	2.40	2.60		
A2	1.40	1.50	1.60		
D	20.32	20.57	20.82		
Е	15.37	15.62	15.87		
E2	4.96	5.08	5.20		
е	~	5.56	~		
L	19.75	20.00	20.25		
L1	3.69	3.81	3.93		
ØΡ	3.51	3.58	3.65		
Q	5.34	5.46	5.58		
S	5.34	5.46	5.58		
b	1.17	1.26	1.35		
b2	1.53	1.65	1.77		
b4	2.42	2.54	2.66		
С	0.51	0.61	0.71		
D1	13.08	~	~		
D2	0.51	0.93	1.35		
E1	12.81	~	~		
ØP1	6.60	6.80	7.00		

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